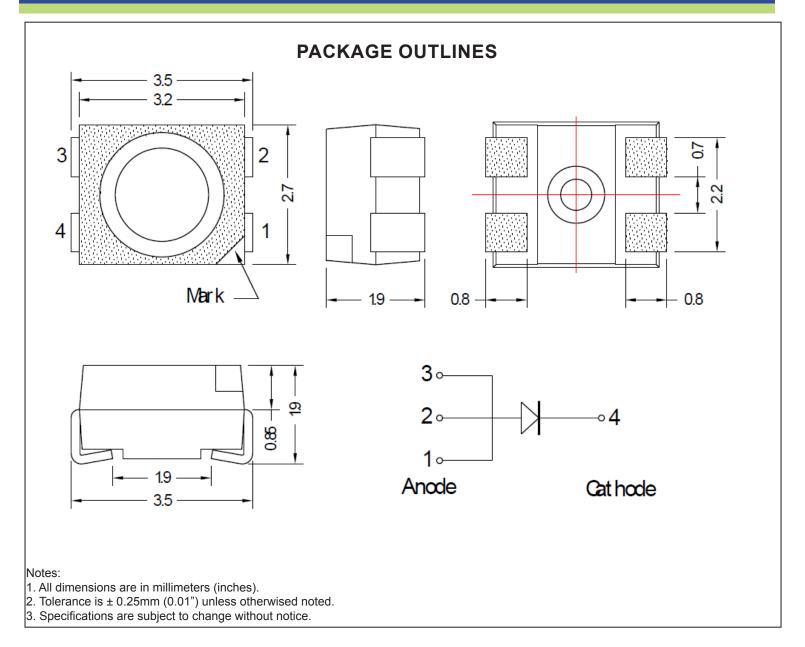


# SPECIFICATION

CSP1311B2C-4



Part Number	Chip Material	Color of Emission	Lens Type	Viewing Angle	
CSP1311B2C-4	InGaN	Blue	Water Clear	120°	





# **ABSOLUTE MAXIMUM RATINGS**

### (TA=25°C)

Parameter	Symbol	Max Rating	Unit	
Forward Current	lF	30	mA	
Reverse Current @ 5V	Vr	10	μA	
Power Dissipation	Pd	108	mW	
Operating Temperature Range	Тор	-30~+100	°C	
Storage Temperature Range	Тѕтс	-40~+100	°C	
Peak Pulsing Current (1/10 duty f = 10KHz)	lfp	100	mA	
Soldering Temperature	TSOL	Max 260°C for 10 sec Max		

# OPTICAL-ELECTRICAL CHARACTERISTICS

(TA=25°C)

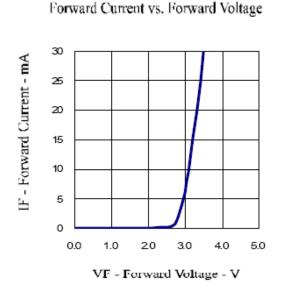
Deremeter	Symbol	Test Condition	Value			Unit
Parameter			Min	Тур	Max	Unit
Luminous Intensity	١v	IF = 50mA	240	340	-	mcd
Forward Voltage	Vf	IF = 50mA	-	3.2	3.6	V
Reverse Leakage Current	lr	VR = 5V	-	-	10	μA
Viewing Angle at 50% Iv	201/2	IF = 50mA	-	120	-	Deg
Peak Wavelength	λP	IF = 50mA	-	465	-	nm
Dominant Wavelength	λD	IF = 50mA	460	470	480	nm

\*Tolerance of viewing angle: -10 / +5 deg.

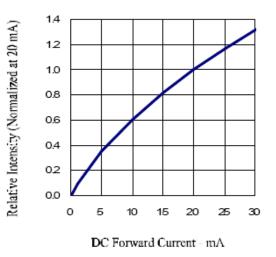




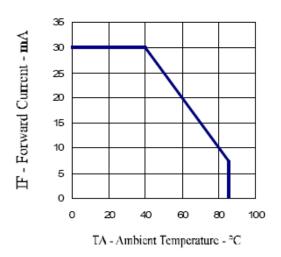
# **OPTICAL CHARACTERISTIC CURVES**

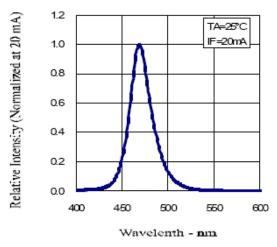


Relative Intensity vs. Forward Current



Forward Current vs. Ambient Temperature





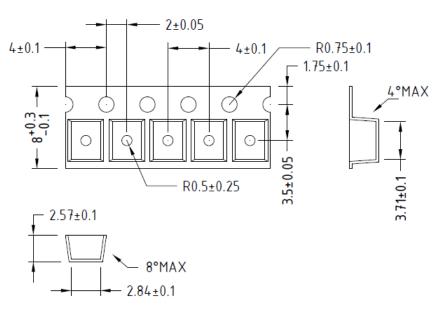
Relative Intensity vs. Wavelength



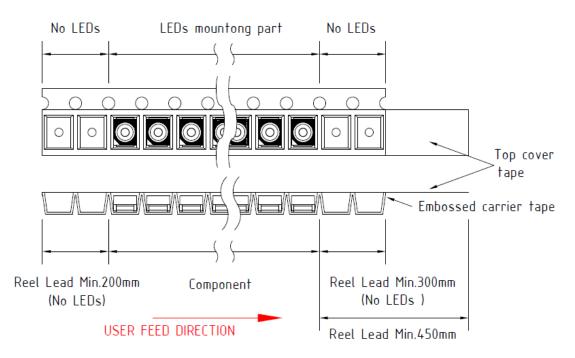


### PACKAGING SPECIFICATION

### **TAPE DIMENSION**



#### TAPE LEADER AND TRAILER DIMENSION



#### Notes:

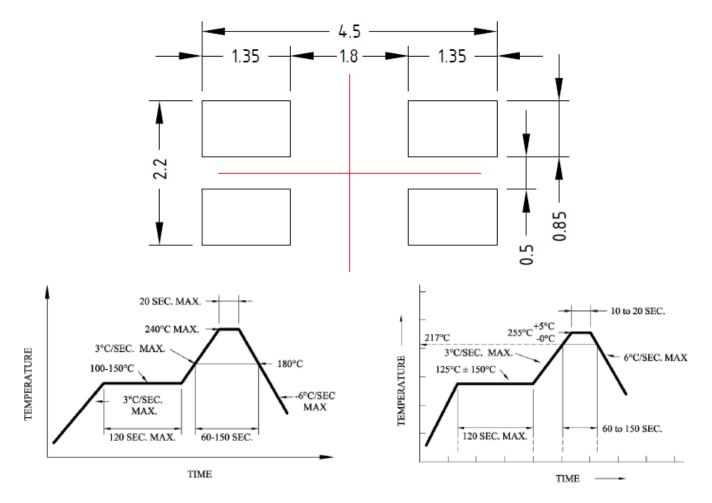
- 1. Empty component pockets are sealed with top cover tape
- 2. The maximum number of missing lamps is two.
- 3. 2000 pcs/reel



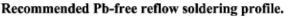


# SOLDERING CONDITIONS

### **RECOMMENDED SOLDERING PAD PATTERN**







- Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used. It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.
- Reflow soldering should not be done more than two times.
- When soldering, do not put stress on the LEDs during heating.
- After soldering, do not warp the circuit board

